

Tgrease[™] 300X Series Thermally Conductive Grease

Preliminary



HIGH PERFORMANCE THERMAL GREASE

Tgrease[™] 300X is a silicone-based thermal grease for use in high performance CPU's and GPU's. Tgrease[™] 300X has a high thermal conductivity of 3.0 W/mK and superior wetting characteristics, resulting in a very low thermal resistance and excellent long term reliability. Tgrease[™] 300X has been formulated not to sag or drip with a high thixotropic index for ease of application and reliability.

FEATURES AND BENEFITS

- Low thermal resistance
- Excellent long term stability
- RoHS compliant
- Resists pump out through novel gel technology
- Available in 1kg (quart container), custom syringes

APPLICATIONS

- Computer CPUs and GPUs
- Telecommunications infrastructure
- Network Hardware
- Automotive electronics
- Consumer electronics

Typical Properties		Test Method
Color	Gray	Visual
Density	2.87 g/cc	Helium Pycnometer
Viscocity	400,000 cP	Brookfield DV-II Helipath Spindle T-F 20 RPMs
Thixotropic Index	3.35	Brookfield Viscometer RPMs
Thermal Resistance @ 50 psi @ 344.7 kPA	0.013°C-in²/W 0.084°C-cm²/W	ASTM D5470 (modified)
Thermal Conductivity	3.0 W/mk	Hot disk thermal constants analyzer
Bond Line Thickness	0.001 in, 25 microns	

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

STORAGE

Store between 15 and 45°C and a maximum humidity of 50%. Do not store in freezer or refrigerator below 5°C.

APPLICATION

Screen print using a mesh of 61 treads per inch (TPI) or less is recommended for easiest application, however the grease has been successfully applied using up to a 140 TPI mesh (The higher the number = smaller mesh opening). If applying from a can, mix can well prior to use. Dispense via syringe or cartridge by hand or mechanically.

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